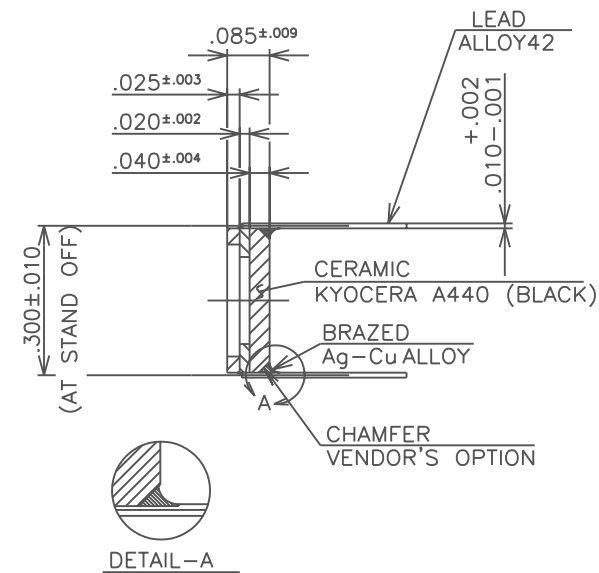
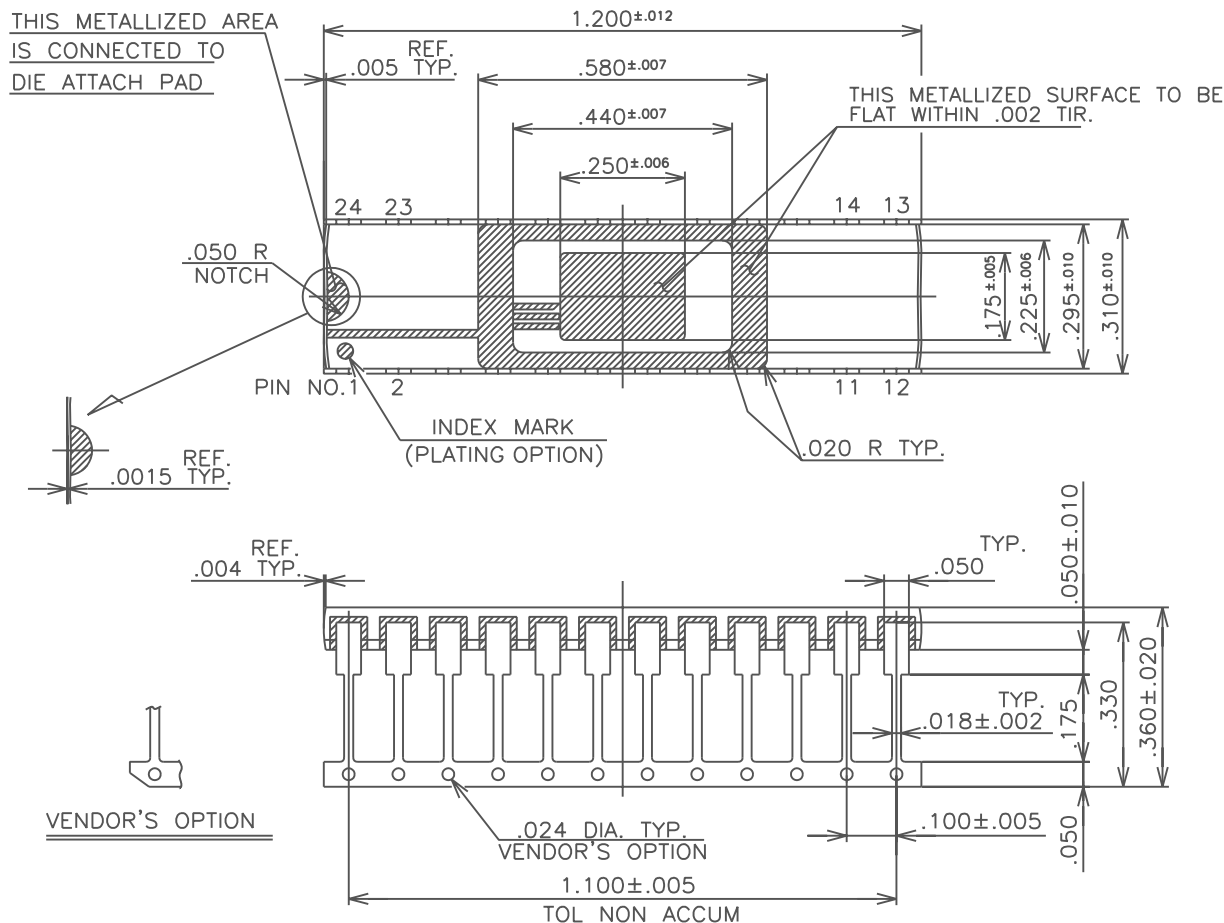


# SSM P/N CSB02402



## NOTES

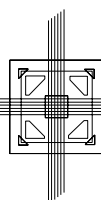
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.3 Ω MAX.
6. DIE ATTACH PAD TO BE ELECTRICALLY CONNECTED TO BONDING PAD "GND".

SB024M831-1 S=0 D=0

| MODIFICATION |                                       |  |  |  |      | NAME                        | TOLERANCE                  | DRAWN    | CHECKED                | APPROVED | DATE       |
|--------------|---------------------------------------|--|--|--|------|-----------------------------|----------------------------|----------|------------------------|----------|------------|
|              | REDRAWN : (CAD DATA)                  |  |  |  |      | 24 LEAD SIDE BRAZED PACKAGE | UNLESS OTHERWISE SPECIFIED | M.S      | S.T/T.A                | M.K      | AUG.06.'91 |
|              | ADDED : .018 TYP. MIN.                |  |  |  |      | SCALE 4 / 1                 | MATERIAL AS INDICATED      | ±.005    |                        |          |            |
|              | ADDED : .005REF., .0015REF., .004REF. |  |  |  |      |                             | THIRD ANGLE PROJECTION     |          |                        |          |            |
| CHANGED      |                                       |  |  |  | DATE | DRAWN                       | CHECKED                    | APPROVED | DRAWING NO. KD-82831-C |          |            |
|              |                                       |  |  |  |      |                             |                            |          | SHEET 1/2              |          |            |

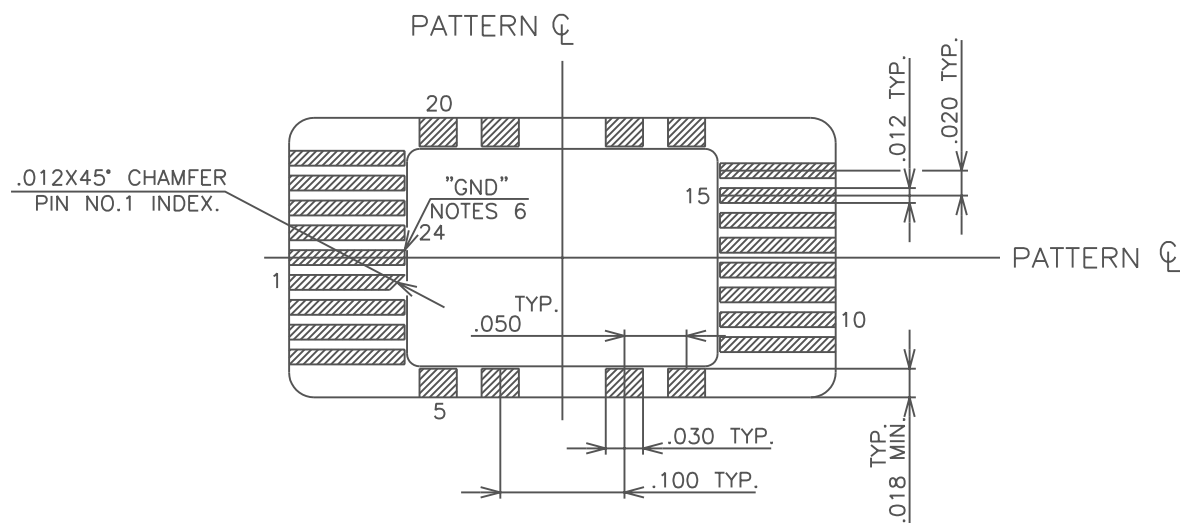


KYOCERA CORPORATION  
KYOTO JAPAN



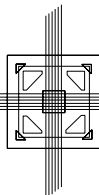
**SPECTRUM**  
SEMICONDUCTOR MATERIALS, INC.

www.spectrum-semi.com Phone: 408.435.5555 Fax: 408.435.8226



### BONDING PATTERN

|              |         |      |       |         |          |                                                                                       |                                    |                           |         |              |            |
|--------------|---------|------|-------|---------|----------|---------------------------------------------------------------------------------------|------------------------------------|---------------------------|---------|--------------|------------|
| MODIFICATION |         |      |       |         |          | NAME                                                                                  | TOLERANCE                          | DRAWN                     | CHECKED | APPROVED     | DATE       |
|              |         |      |       |         |          | 24 LEAD SIDE BRAZED PACKAGE                                                           | UNLESS OTHERWISE SPECIFIED         | M.S                       | S.T/T.A | M.K          | AUG.06.'91 |
|              |         |      |       |         |          | SCALE 10 / 1                                                                          | MATERIAL                           |                           |         |              |            |
|              |         |      |       |         |          |                                                                                       | THIRD ANGLE PROJECTION             |                           |         |              |            |
|              | CHANGED | DATE | DRAWN | CHECKED | APPROVED |  | KYOCERA CORPORATION<br>KYOTO JAPAN | DRAWING NO.<br>KD-82831-C |         | SHEET<br>2/2 |            |



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